

<b>INFORMATION DISCLOSURE CITATION</b> (Use several sheets if necessary)	Attorney Docket No.: 46884-5494	Serial No.: 10/585,660
	Applicants Kazuhiro ATSUMI et al.	Page 1 of 2
<b>PTO Form 1449</b>	Filing Date: July 7, 2006	Group Art Unit: Unassigned

### U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Sub Class	Filing Date
	3,629,545	Dec. 21, 1971	Graham et al.			
	4,562,333	Dec. 31, 1985	Taub et al.			
	5,254,833	Oct. 19, 1993	Okiyama			
	5,543,365	Aug. 6, 1996	Wills et al.			
	5,622,540	Apr. 22, 1997	Stevens			
	5,637,244	Jun. 10, 1997	Erokhin			
	5,776,220	Jul. 7, 1998	Allaire et al.			
	5,826,772	Oct. 27, 1998	Ariglio et al.			
	6,055,829	May 2, 2000	Witzmann et al.			
	6,175,096	Jan. 16, 2001	Nielsen			
	6,211,488	Apr. 3, 2001	Hoekstra et al.			
	6,252,197	Jun. 26, 2001	Hoekstra et al.			
	6,257,224	Jul. 10, 2001	Yoshino et al.			
	6,259,058	Jul. 10, 2001	Hoekstra			
	6,322,958	Nov. 27, 2001	Hayashi			
	6,420,678	Jul. 16, 2002	Hoekstra			
	6,489,588	Dec. 3, 2002	Hoekstra et al.			
	2002/0006765	Jan. 17, 2002	Michel et al.			
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	2006/0144828	Jul. 6, 2006	Fukumitsu et al.			

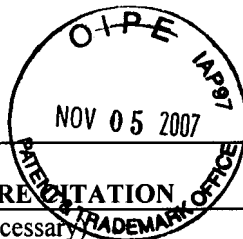
### FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Sub Class	<u>Translation</u> YES NO	
	WO 2004/052586	Jun. 24, 2004	PCT			Abstract	
	46-24989 (corresponds to US 3,629,545)	Jul. 19, 1971	Japan				X
	04-111800	Apr. 13, 1992	Japan			X	
	06-252260	Sep. 9, 1994	Japan			Abstract	
	07-040336	Feb. 10, 1995	Japan			Abstract	
	07-236985	Sep. 12, 1995	Japan			Abstract	
	10-163780	Jun. 19, 1998	Japan			Abstract	
	10-202381	Aug. 4, 1998	Japan			Abstract	
	11-138896	May 25, 1999	Japan			Abstract	
	11-163403	Jun. 18, 1999	Japan			Abstract	
	11-177137	Jul. 2, 1999	Japan			Abstract	
	11-221684	Aug. 17, 1999	Japan			Abstract	
	11-267861	Oct. 5, 1999	Japan			Abstract	
	2000-015467	Jan. 18, 2000	Japan			Abstract	
	2000-219528	Aug. 8, 2000	Japan			Abstract	

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### FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Sub Class	Translation	
					YES	NO
2001-093864	Apr. 6, 2001	Japan			Abstract	

### OTHER DOCUMENTS

(Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.) date, page(s), volume-issue number(s), publisher, city and/or country where published.)

	K. HAYASHI, "Inner Glass Marking by Harmonics of Solid-state Laser", Proceedings of the 45 <sup>th</sup> Laser Materials Processing Conference, December 1998, pp. 23-28, with English abstract.
	T. SANO et al., "Evaluation of Processing Characteristics of Silicon with Picosecond Pulse Laser," Preprints of the National Meeting of Japan Welding Society, No. 66, Apr. 2000, pp. 72-73, with English translation.
	K. MIURA et al., "Formation of Photo-induced Structures in Glasses with Femtosecond Laser," Proceedings of 42 <sup>nd</sup> Laser Materials Processing Conference, Nov. 1997, pp. 105-111.
	T. MIYAZAKI, "Laser Beam Machining Technology," Published by Sangyo-Tosho Inc., May 31, 1991, First Edition. pp. 9-10, with English translation.
	T. YAJIMA et al., <i>New Version Laser Handbook</i> , published by Asakusa Shoten, June 15, 1989, pp. 666-669, with English translation.
	<i>Tooling Machine Series, Laser Machining</i> , published by Taiga Shuppan, Inc., Sept. 10, 1990, pp. 91-96, with English translation.
	T. HIDETSUGU, "Stealth Dicing, Its Principles and Features: A Technology Most Suitable for Dicing Very Thin Semiconductor Wafers," <i>Electronic Material</i> , No. 9, 2002, pp. 17-21, with English translation.
	F. FUKUYO et al., "Stealth Dicing Technology for Ultra Thin Wafer", presented at 2003 ICEP (International Conference on Electronics Packaging), April 16-18, 2003, Tokyo, Japan, pp. 266-269.

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